

[54] LIGHT-EMITTING DIODE SEMICONDUCTOR CHIP WITH LEADS

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[**] Term: 14 Years

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[58] Field of Search D13/99; D26/1; 362/800; 313/499, 500, 501, 512; 357/17, 74

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[57] CLAIM

The ornamental design for a light-emitting diode semiconductor chip with leads, substantially as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a light-emitting diode semiconductor chip with leads showing my new design; FIG. 2 is a front elevational view thereof; FIG. 3 is a side elevational view thereof, as seen from the right side of FIG. 1; FIG. 4 is a side elevational view thereof, as seen from the left side of FIG. 1; FIG. 5 is a top plan view thereof; FIG. 6 is a bottom plan view thereof; FIG. 7 is a perspective view of a light-emitting diode semiconductor chip with leads showing the second embodiment of my new design; FIG. 8 is a front elevational view thereof; FIG. 9 is a side elevational view thereof, as seen from the right side of FIG. 7; FIG. 10 is a side elevational view thereof, as seen from the left side of FIG. 7; FIG. 11 is a top plan view thereof; and FIG. 12 is a bottom plan view thereof.

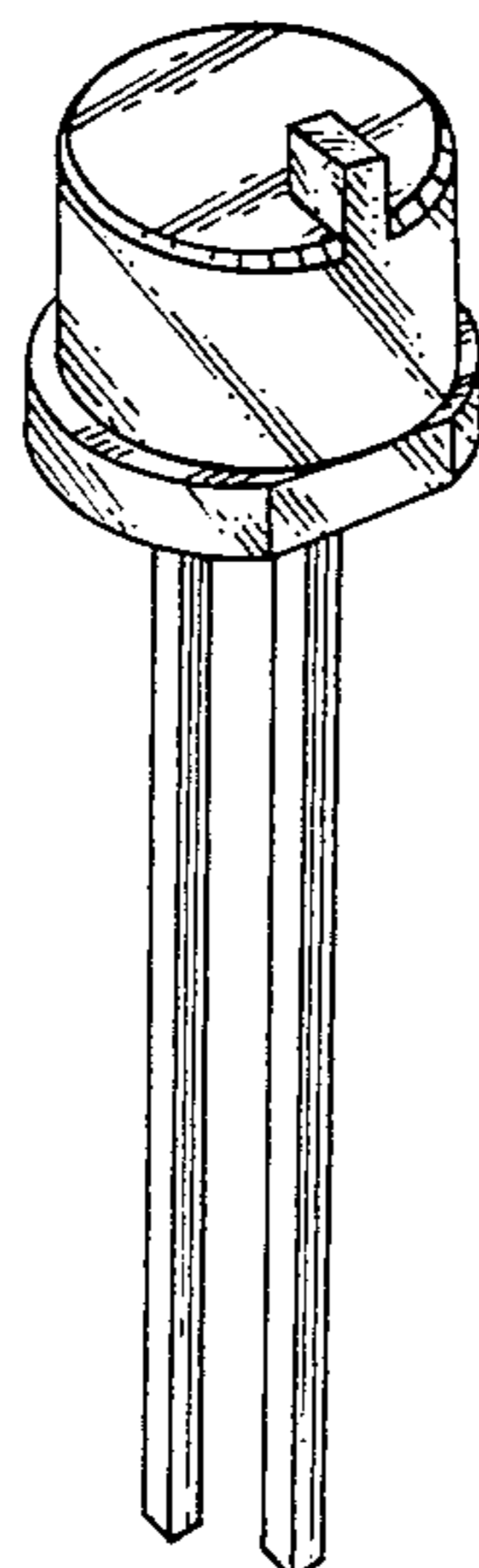


Fig. 1

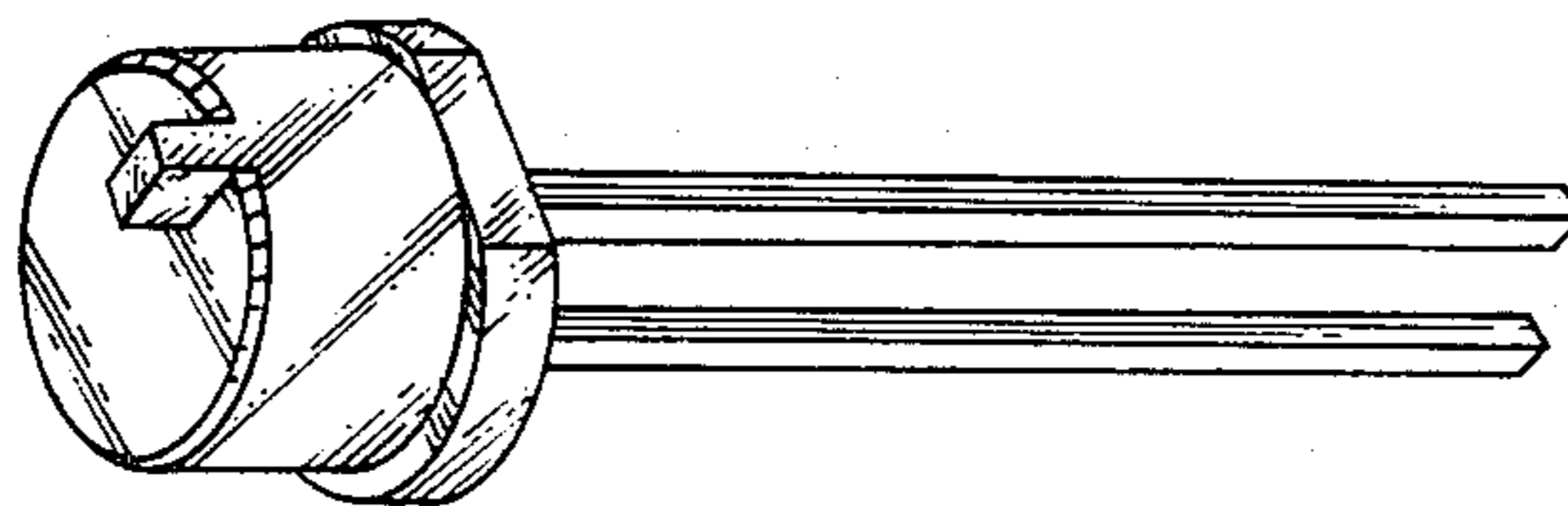


Fig. 2

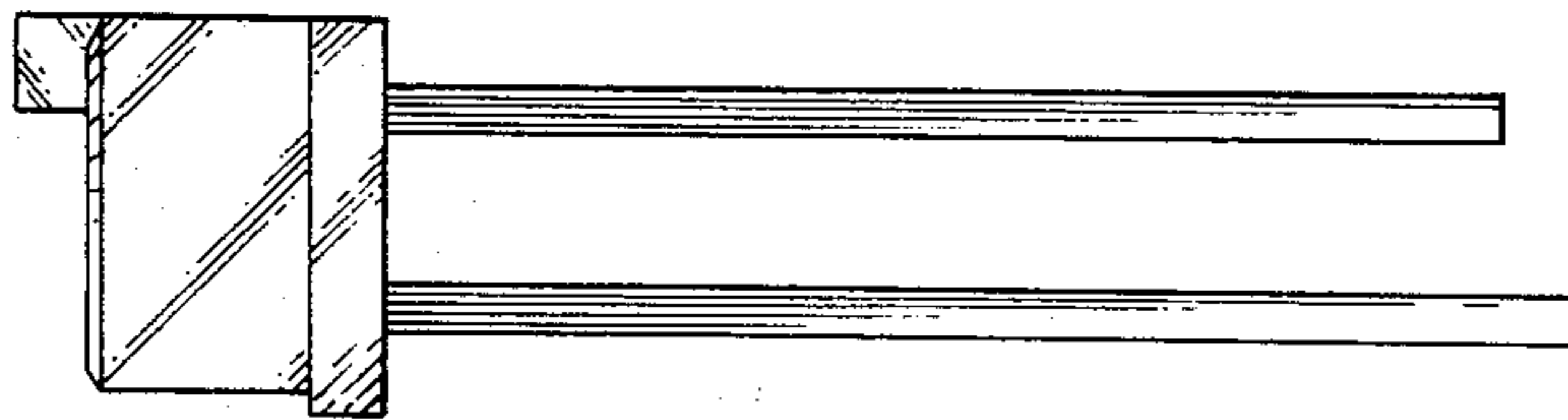


Fig. 3

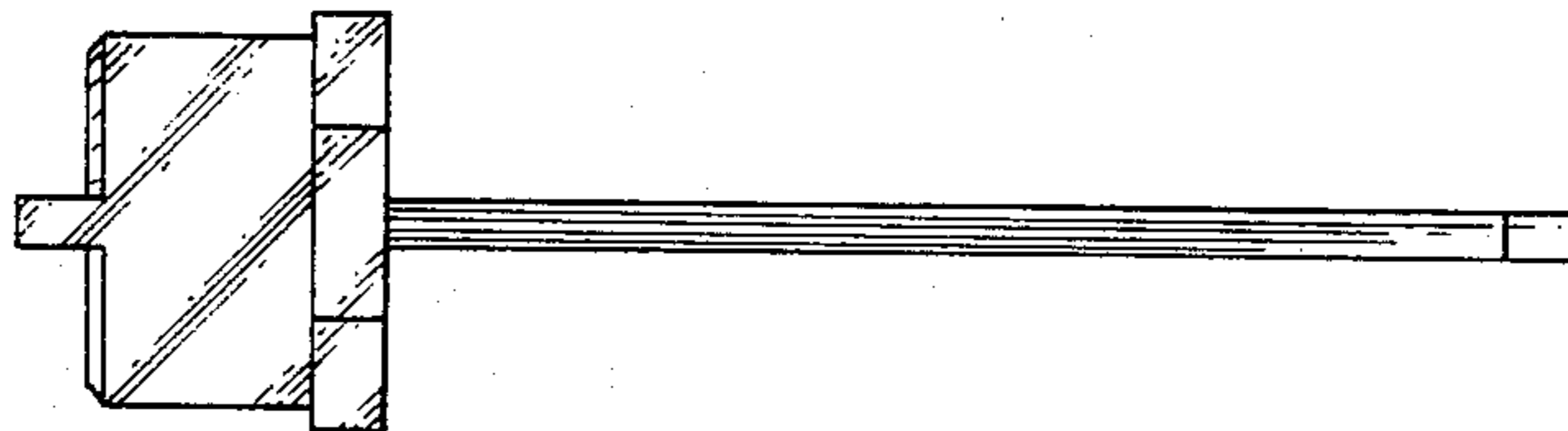


Fig. 4

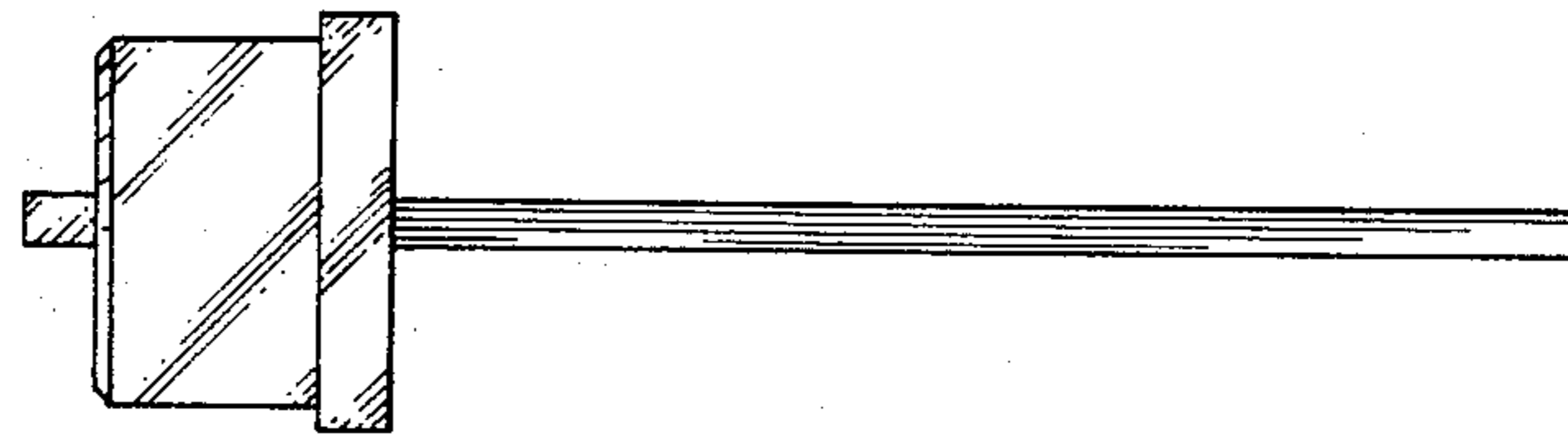


Fig. 5

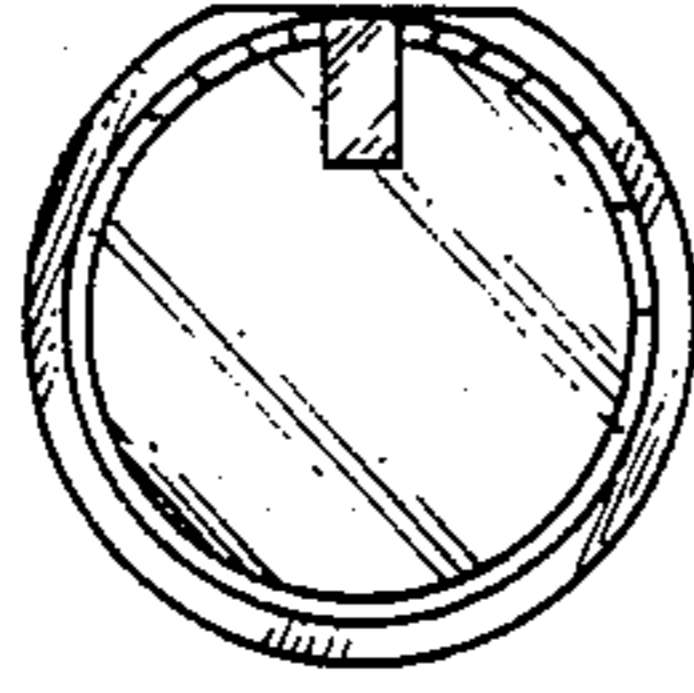


Fig. 6

